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Under the Paperwork Reduction Act or 1986, 110 p		Application Number	Office: U.S. DEPARTMENT OF Control number. retion unless it displays a valid OMB control number. 09/548,946	
TRANSMITTAL FORM (to be used for all correspondence after initial filing)			April 13, 2000	
		Filing Date First Named Inventor	Estacio, Maria Cristina B.	
			2811	
		Group Art Unit	N. Parekh	
		Examiner Name	018865-004500US	
tal Number of Pages in This Submission		Attorney Docket Number	018888	
		OSURES (check all that apply)	After Allowance Communication to	
Fee Transmittal Form	Assigr	nment Papers Application)	Group	
Fee Attached	☐ Drawi		Appeal Communication to Board of Appeals and Interferences	
Amendment / Response	Licen	sing-related Papers	Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)	
After Final	Petition Routing Slip (PTO/SB/69) and Accompanying Petition		Proprietary Information	
Affidavits/declaration(s)	Petition to Convert to a Provisional Application		Status Letter	
Extension of Time Request	Power of Attorney, Revocation Change of Correspondence Address		Other Enclosure(5) (please Identify below):	
	Terminal Disclaimer		Return Postcard	
Express Abandonment Request	Requ	uest for Refund		
Information Disclosure Statement	CD.	Number of CD(s)		
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Response to Missing Parts/ Incomplete Application		- <del></del>	NOV 29 200	
Response to Missing Parts under 37 CFR 1.52 or 1.53			TECHNOLOGY CENTER	
	ATURE O	F APPLICANT, ATTORNEY,	OR AGENT	
Firm Townsend and T	ownsend a	nd Crew LLP	/	
and Kevin T. LeMond	Kevin T. LeMond Reg. No. 85,933			
Signature	lon army			
Date 11/29/01	11/29/01			
		CERTIFICATE OF MAILING		
I hereby certify that this correspondence class mail in an envelope addressed to:	e is being d Assistant (	eposited with the United States Pr Commissioner for Patents, Washin	ostal Service with sufficient postage as first ngton, O.C. 20231 on this date: 11/29/01	
Typed or printed name Lata Olivier	r			
Signature	Date 11/29/01  stimeted to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any required to complete this form should be send to the Chief Information Officer, U.S. Patent and Trademark or required to complete this form should be send to the Chief Information Officer.			

&CREW

Atty Docket No. 018865-004500US

PTO FAX NO.:

1 703 - 872-9318

ATTENTION:

Examiner N. Parekh

TELEPHONE NO.:

1 703 308-2772

Group Art Wnit 2811

## OFFICIAL COMMUNICATION

# FOR THE PERSONAL ATTENTION OF

## **EXAMINER N. Parekh**

### CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following document(s) in re Application of Maria Christine B. Estacio, Application No. 09/548,946, filed April 13, 2000 for FLIP CLIP ATTACH AND COPPER CLIP ATTACH ON MOSFET DEVICE is being facsimile transmitted to the Patent and Trademark Office on the date shown below.

#### Document(s) Attached

1. Trasnmittal Form

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2. Amendment

NOV 29 2001

Number of pages being transmitted, including this page: 8

**TECHNOLOGY CENTER 2800** 

Dated: 11/29/01

Lata Olivier

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**2**003/008

Attorney Docket No.: 018865-004500US

Client Ref. No.: 17732-1394

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Examiner:

N. Parekh

Maria Christine B. Estacio

Art Unit:

2811

Application No.: 09/548,946

AMENDMENT

Filed: April 13, 2000

For: FLIP CLIP ATTACH AND

COPPER CLIP ATTACH ON MOSFET

DEVICE

FAX COPY RECEIVED

NOV 29 2001

TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Office Action mailed August 29, 2001, please amend the above-identified application as follows:

### IN THE CLAIMS:

Please cancel claims 1-4.

Please amend the following claim:

(Amended) Achip device comprising:

a leadframe including source and gate connections;

a bumped die including solder bumps on a top side, the bumped die being

attached to the leadframe such that the solder bumps contact the source and gate

connections; and

a copper clip attached to a backside of the bumped die such that the copper

clip contacts drain regions of the bumped die and a lead rail.